# 27C100 1M (128K x 8) CHMOS EPROM

- Pin Compatible with 28-Pin 1 Mbit MASK ROM
- Low Power Consumption — 30 mA Max. Active
  - 100 µA Max. Standby
- **CMOS and TTL Compatibility**

- High Performance
  - ± 10% V<sub>CC</sub>
  - 120 ns Maximum Access Time
- Quick-Pulse Programming™ Algorithm
  - Programming as Fast as 15 Seconds
- **■** 32-Pin CERDIP and PDIP Packages

Intel's 27C100 is a 5V-only, 1,048,576 bit, Erasable Programmable Read Only Memory organized as 131,072 bytes of 8 bits. It employs advanced CHMOS\* III E circuitry for systems requiring low power, high speed performance and noise immunity. This device is pin compatible with 28-pin 1 Mbit MASK ROMs.

The 27C100's 120 ns speed (t<sub>ACC</sub>) offers no-wait-state operation with high-performance CPUs in applications ranging from numerical control to office automation and telecommunications. The 27C100 is equally at home in both TTL and CMOS environments.

Intel offers two DIP profile options to meet your prototyping and production needs. The windowed ceramic DIP (CERDIP) package provides erasability and reprogrammability for prototyping and early production. Once the design is in full production, the plastic DIP (PDIP) one-time programmable part provides a lower cost alternative that is well adapted for auto insertion. This EPROM solution is particularly well-suited for "Just-In Time" code customization to meet specific geographic or application needs in your product line. The Quick-Pulse ProgrammingTM Algorithm provides fast, reliable programming.

\*CHMOS is a patented process of Intel Corporation.

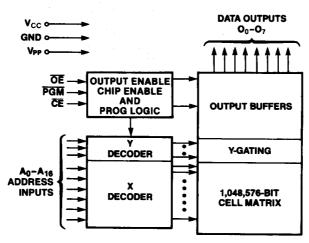


Figure 1. Block Diagram

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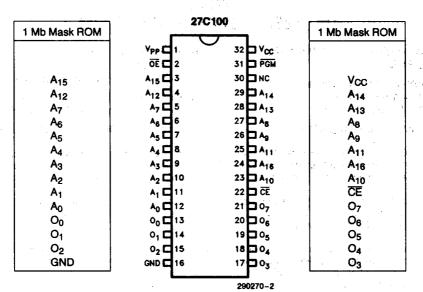


Figure 2. DIP Pin Configuration

#### Pin Names

A <sub>0</sub> -A <sub>16</sub>	ADDRESSES
O <sub>0</sub> -O <sub>7</sub>	OUTPUTS
ŌĒ	OUTPUT ENABLE
CE	CHIP ENABLE
PGM	PROGRAM
NC	NO CONNECT

#### **ABSOLUTE MAXIMUM RATINGS\***

Operating Temperature0°C to 70°C(1)
Temperature under Bias 10°C to 80°C
Storage Temperature65°C to 125°C
Voltage on Any Pin (except A <sub>9</sub> , V <sub>CC</sub> and V <sub>PP</sub> ) with Respect to GND0.6V to 6.25V <sup>(2)</sup>
Voltage on A <sub>9</sub> with Respect to GND0.6V to 13V(2)
V <sub>PP</sub> Program Voltage with Respect to GND 0.6V to 14V(2)
V <sub>CC</sub> Supply Voltage with Respect to GND0.6V to 7V(2)

NGTICE. This data sheet contains preliminary information on new products in production. The specifications are subject to change without notice. Verify with your local Intel Sales office that you have the latest data sheet before finalizing a design.

\*WARNING: Stressing the device beyond the "Absolute Maximum Ratings" may cause permanent damage. These are stress ratings only. Operation beyond the "Operating Conditions" is not recommended and extended exposure beyond the "Operating Conditions" may affect device reliability.

### READ OPERATION DC CHARACTERISTICS $V_{CC} = 5.0V \pm 10\%$

Symbol	Parameter	Notes	Min	Тур	Max	Unit	Test Condition
ILI	Input Load Current	7	19.15	0.01	1.0	μΑ	V <sub>IN</sub> = 0V to 5.5V
اله	Output Leakage Current				±10	μΑ	$V_{OUT} = 0V \text{ to } 5.5V$
ISB	V <sub>CC</sub> Standby Current				1.0	.mA	CE = VIH
					100	μΑ	$\overline{CE} = V_{CC} \pm 0.2V$
lcc	V <sub>CC</sub> Operating Current	3	e e session in a	.,	30	mA	f = 5 MHz, CE = V <sub>IL</sub> , t <sub>OUT</sub> = 0 mA
lpp	V <sub>PP</sub> Operating Current	3	. 1 (141-4)		10	μΑ	$V_{PP} = V_{CC}$
los	Output Short Circuit Current	4, 6			100	mA	
V <sub>IL</sub>	Input Low Voltage		-0.5		0.8	٧	
V <sub>IH</sub>	Input High Voltage		2.0		V <sub>CC</sub> + 0.5	V	
VOL	Output Low Voltage				0.45	٧	I <sub>OL</sub> = 2.1 mA
V <sub>OH</sub>	Output High Voltage	·	2.4			٧	I <sub>OH</sub> = -400 μA
V <sub>PP</sub>	V <sub>PP</sub> Operating Voltage	5	V <sub>CC</sub> - 0.7.		V <sub>CC</sub>	٧	

#### NOTES:

- 1. Operating temperature is for commercial product defined by this specification.
- 2. Minimum DC voltage is -0.5V on input/output pins. During transitions, this level may undershoot to -2.0V for periods <20 ns. Maximum DC voltage on input/output pins is  $V_{CC} + 0.5V$  which, during transitions, may overshoot to  $V_{CC} + 2.0V$  for periods <20 ns.
- 3. Maximum active power usage is the sum  $l_{pp} + l_{CC}$ . Maximum current value is with outputs  $O_0 O_7$  unloaded.
- 4. Output shorted for no more than one second. No more than one output shorted at a time.
- 5. Vpp may be connected directly to V<sub>CC</sub> or may be 1 diode voltage drop below V<sub>CC</sub>. V<sub>CC</sub> must be applied simultaneously or before V<sub>PP</sub> and removed simultaneously or after V<sub>PP</sub>.
- 6. Sampled, not 100% tested.
- 7. Typical limits are at  $V_{CC} = 5V$ ,  $T_A = 25$ °C.
- 8. Absolute Maximum rating applies to NC pins.



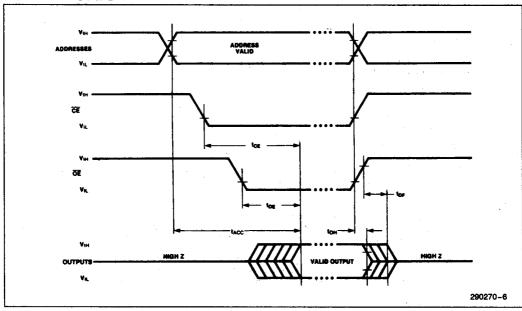
# READ OPERATION AC CHARACTERISTICS(1) VCC = 5.0V ± 10%

Vei	rsions <sup>(4)</sup>	V <sub>CC</sub> ± 1	0%	27C100	-120V10	1	-150V10 0-150V10	1	-200V10 -200V10	Unit
Symbol	Paran	neter	Notes	Min	Max:	Min	Max	Min	Max	
tACC	Address to O	utput Delay			120		150		200	ns
tCE	CE to Output	Delay	2		120		150		200	ns
t <sub>OE</sub>	OE to Output	Delay	2		55		60		.70	ns
t <sub>DF</sub>	OE High to O	utput High Z	3		30		50		60	ns
<sup>t</sup> OH	Output Hold f Addresses, C Change— Wh Occurs First	E or OE	3	0		0		0		ns

#### NOTES:

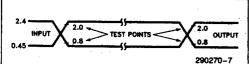
- See AC Input/Output Reference Waveform for timing measurements.
   DE may be delayed up to t<sub>CE</sub>-t<sub>OE</sub> after the falling edge of DE without impact on t<sub>CE</sub>.
- 3. Sampled, not 100% tested.
- 4. Model Number Prefixes: No Prefix = CERDIP, P = PDIP.

# **AC WAVEFORMS**



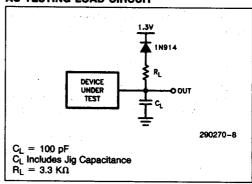
Symbol	Parameter	Typ(5)	Max	Unit	Condition
C <sub>IN</sub>	Input Capacitance	4	8	pF	VIN = OV
COUT	Output Capacitance	8	12	pF	V <sub>OUT</sub> = 0V
C <sub>VPP</sub>	V <sub>PP</sub> Capacitance	16	25	рF	V <sub>PP</sub> = 0V

#### AC INPUT/OUTPUT REFERENCE WAVEFORM



AC test inputs are driven at V<sub>OH</sub> (2.4 V<sub>TTL</sub>) for a Logic "1" and V<sub>OL</sub> (0.45 V<sub>TTL</sub>) for a Logic "0". Input timing begins at V<sub>IH</sub> (2.0 V<sub>TTL</sub>) and V<sub>IL</sub> (0.8 V<sub>TTL</sub>). Output timing ends at V<sub>IH</sub> and V<sub>IL</sub>. Input rise and fall times (10% to 90%)  $\leq$  10 ns.

#### **AC TESTING LOAD CIRCUIT**



### **DEVICE OPERATION**

The Mode Selection table lists 27C100 operating modes. Read Mode requires a single 5V power supply. All inputs, except V<sub>CC</sub> and V<sub>PP</sub>, and A<sub>8</sub> during intelligent Identifier Mode, are TTL or CMOS.

Table 1. Mode Selection

	and the second			MAGG 00	000011				
Mode	Notes	CE	ŌĒ	PGM	Ag	A <sub>0</sub>	V <sub>PP</sub>	Vcc	Outputs
Read	1	V <sub>IL</sub>	V <sub>IL</sub>	X	Х	Х	Vcc	Vcc	D <sub>OUT</sub>
Output Disable		V <sub>IL</sub>	V <sub>IH</sub>	×	Х	Х	Vcc	Vcc	High Z
Standby		V <sub>IH</sub>	Х	X	Х	Х	Vcc	Vcc	High Z
Program	2	V <sub>IL</sub>	V <sub>IH</sub>	V <sub>IL</sub>	Х	Х	V <sub>PP</sub>	V <sub>CP</sub>	D <sub>IN</sub>
Program Verify		V <sub>IL</sub>	V <sub>IL</sub>	VIH	Х	Х	V <sub>PP</sub>	V <sub>CP</sub>	D <sub>OUT</sub>
Program Inhibit		V <sub>IH</sub>	Х	х	Х	Х	V <sub>PP</sub>	V <sub>CP</sub>	High Z
inteligent Identifier		V <sub>IL</sub>	VIL	×	V <sub>ID</sub>	VIL	Vcc	Vcc	89H
-Manufacturer -Device	2, 3	V <sub>IL</sub>	V <sub>IL</sub>	Х	V <sub>ID</sub>	VIH	V <sub>CC</sub>	V <sub>CC</sub>	32H

#### NOTES:

- 1. X can be VIL or VIH.
- 2. See DC Programming Characteristics for  $V_{CP}$ ,  $V_{PP}$  and  $V_{ID}$  voltages.
- 3.  $A_1 A_8$ ,  $A_{10} A_{16} = V_{IL}$ .
- 4. Sampled, not 100% tested.
- 5. Typical limits are at  $V_{CC} = 5V$ ,  $T_A = 25$ °C.

#### **Read Mode**

The 27C100 has two control functions, both must be enabled to obtain data at the outputs.  $\overline{CE}$  is the power control and device select.  $\overline{OE}$  controls the output buffers to gate data to the outputs. With addresses stable, the address access time ( $t_{ACC}$ ) equals the delay from  $\overline{CE}$  to output ( $t_{CE}$ ). Outputs display valid data  $t_{OE}$  after  $\overline{OE}$ 's falling edge, assuming  $t_{ACC}$  and  $t_{CE}$  times are met.

V<sub>CC</sub> must be applied simultaneously or before V<sub>PP</sub> and removed simultaneously or after V<sub>PP</sub>.

# **Two Line Output Control**

EPROMs are often used in larger memory arrays. Intel provides two control inputs to accommodate multiple memory connections. Two-line control provides for:

- a) lowest possible memory power dissipation
- complete assurance that data bus contention will not occur

To efficiently use these two control inputs, an address decoder should enable  $\overline{CE}$  while  $\overline{OE}$  should be connected to all memory devices and the system's  $\overline{READ}$  control line. This assures that only selected memory devices have active outputs while deselected memory devices are in Standby Mode.

# **Standby Mode**

Standby Mode substantially reduces  $V_{CC}$  current. When  $\overline{CE}=V_{IH}$ , the outputs are in a high impedance state, independent of  $\overline{OE}$ .

# Program Mode

Caution: Exceeding 14V on  $\mathbf{V}_{PP}$  will permanently damage the device.

Initially, and after each erasure, all EPROM bits are in the "1" state. Data is introduced by selectively programming "0s" into the desired bit locations. Although only "0s" are programmed, the data word can contain both "1s" and "0s". Ultraviolet light erasure is the only way to change "0s" to "1s".

Program Mode is entered when  $V_{PP}$  is raised to 12.75V. Data is introduced by applying an 8-bit word to the output pins. Pulsing  $\overline{PGM}$  low while  $\overline{CE} = V_{IL}$  and  $\overline{OE} = V_{IH}$  programs that data into the device.

# **Program Verify**

A verify should be performed following a program operation to determine that bits have been correctly programmed with  $V_{CC}$  at 6.25V, a substantial program margin is ensured. The verify is performed with  $\overline{CE}$  at  $\overline{V_{IL}}$  and  $\overline{PGM}$  at  $\overline{V_{IH}}$ . Valid data is available  $\overline{V_{OE}}$  after  $\overline{OE}$  falls low.

### **Program Inhibit**

Program Inhibit Mode allows parallel programming of multiple EPROMs with different data. CE-high inhibits programming of non-targeted devices. Except for CE, parallel EPROMs may have common inputs.

# inteligent Identifier™ Mode

The inteligent Identifier Mode will determine an EPROM's manufacturer and device type, allowing programming equipment to automatically match a device with its proper programming algorithm.

This mode is activated when a programmer forces  $12V \pm 0.5V$  on  $A_9$ . With  $A_1-A_8$ ,  $A_{10}-A_{16}$ ,  $\overline{CE}$  and  $\overline{OE}$  at  $V_{IL}$ ,  $A_0 = V_{IL}$  will present the manufacturer's code and  $A_0 = V_{IH}$  the device code. This mode functions in the 25°C  $\pm$ 5°C ambient temperature range required during programming.

# **ROM Compatibility**

The 27C100 is compatible with 28-pin mask ROMs to provide a reprogrammable memory solution during prototyping and early production. Reference Figure 2; design in the 32-pin socket for the 27C100 EPROM and connect V<sub>CC</sub> to pins 1, 30 and 32. If the EPROM is replaced with a MROM, socket pins 1, 2, 31 and 32 are no longer required.

#### SYSTEM CONSIDERATIONS

EPROM power switching characteristics require careful device decoupling. System designers are interested in 3 supply current issues—standby current levels (I<sub>CC</sub>), and transient current peaks produced by falling and rising edges of CE. Transient current magnitudes depend on the device outputs' capacitive and inductive loading.

Two-Line Control and proper decoupling capacitor selection will suppress transient voltage peaks. Each device should have a 0.1  $\mu F$  ceramic capacitor connected between its V<sub>CC</sub> and GND. This high frequency, low inherent-inductance capacitor should be placed as close as possible to the device. Additionally, for every eight devices, a 4.7  $\mu F$  electrolytic capacitor should be placed at the array's power supply connection between V<sub>CC</sub> and GND. The bulk capacitor will overcome voltage slumps caused by PC board trace inductances.

#### **ERASURE CHARACTERISTICS**

Erasure begins when EPROMs are exposed to light with wavelengths shorter than approximately 4000 Angstroms (Å). It should be noted that sunlight and certain fluorescent lamps have wavelengths in the 3000–4000Å range. Data shows that constant exposure to room level fluorescent lighting can erase an EPROM in approximately 3 years, while it takes approximately 1 week when exposed to direct sunlight. If the device is exposed to these lighting conditions for extended periods, opaque labels should be placed over the window to prevent unintentional erasure.

The recommended erasure procedure is exposure to ultraviolet light of wavelength 2537Å. The integrated dose (UV intensity  $\times$  exposure time) for erasure should be a minimum of 15 Wsec/cm². Erasure time is approximately 15 to 20 minutes using an ultraviolet lamp with a 12000  $\mu\text{W/cm}^2$  power rating. The EPROM should be placed within 1 inch of the lamp tubes. An EPROM can be permanently damaged if the integrated dose exceeds 7258 Wsec/cm² (1 week @ 12000  $\mu\text{W/cm}^2$ ).

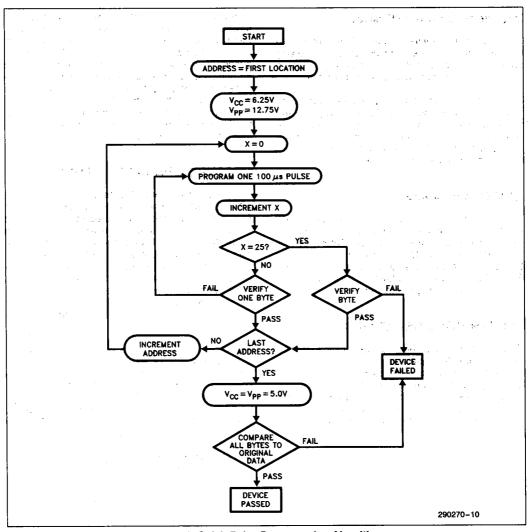


Figure 3. Quick-Pulse Programming Algorithm

### **Quick-Pulse Programming Algorithm**

The Quick-Pulse programming algorithm programs Intel's 27C100. Developed to substantially reduce programming throughput, this algorithm can program the 27C100 as fast as 15 seconds. Actual programming time depends on programmer overhead.

The Quick-Pulse programming algorithm employs a 100  $\mu$ s pulse followed by a byte verification to determine when the addressed byte has been successfully programmed. The algorithm terminates if 25 attempts fail to program a byte.

The entire program-pulse/byte verify sequence is performed with V<sub>PP</sub> = 12.75V and V<sub>CC</sub> = 6.25V. When programming is complete, all bytes are compared to the original data with V<sub>CC</sub> = V<sub>PP</sub> = 5.0V.

# DC PROGRAMMING CHARACTERISTICS T<sub>A</sub> = 25°C ±5°C

Symbol	Parameter	Notes	Min	Тур	Max	Unit	Test Condition
lu	Input Load Current				1	μÁ	$V_{IN} = V_{IL} \text{ or } V_{IH}$
ICP	V <sub>CC</sub> Program Current	1			40	mA	CE = PGM = VIL
lpp	V <sub>PP</sub> Program Current	1	w 19		.50	mA	CE = PGM = VIL
V <sub>IL</sub>	Input Low Voltage		-0.1		0.8	V	
V <sub>IH</sub>	Input High Voltage		2.4		6.5	٧	
V <sub>OL</sub>	Output Low Voltage (Verify)			·	0.45	٧	I <sub>OL</sub> = 2.1 mA
V <sub>OH</sub>	Output High Voltage (Verify)		3.5			V	$I_{OH} = -2.5  \text{mA}$
V <sub>ID</sub>	A <sub>9</sub> int <sub>e</sub> ligent Identifier Voltage		11.5	12.0	12.5	٧	
V <sub>PP</sub>	V <sub>PP</sub> Program Voltage	2, 3	12.5	12.75	13.0	V	
V <sub>CP</sub>	V <sub>CC</sub> Supply Voltage (Program)	2	6.0	6.25	6.5	٧	

# AC PROGRAMMING CHARACTERISTICS(4) $T_A = 25^{\circ}C \pm 5^{\circ}C$

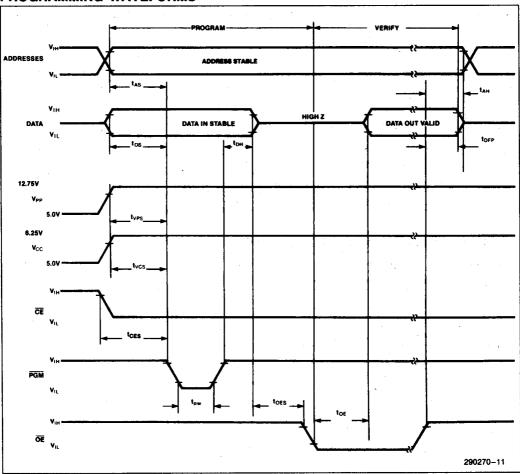
Symbol	Parameter	Notes	Min	Тур	Max	Unit
tvcs	V <sub>CP</sub> Setup Time	2	2			μs
t <sub>VPS</sub>	V <sub>PP</sub> Setup Time	2	2			μs
t <sub>CES</sub>	CE Setup Time		2	•		μs
t <sub>AS</sub>	Address Setup Time		2			μѕ
t <sub>DS</sub>	Data Setup Time		2			μs
t <sub>PW</sub>	PGM Program Pulse Width		95	100	105	μs
t <sub>DH</sub>	Data Hold Time		2			μs
toes	OE Setup Time		2			μs
toE	Data Valid from OE	5			150	ns
t <sub>DFP</sub>	OE High to Output High Z	5, 6	0		130	ns
t <sub>AH</sub>	Address Hold Time		0			μs

#### NOTES:

- 1. Maximum current is with outputs 0<sub>0</sub>-0<sub>7</sub> unloaded.
- 2. V<sub>CC</sub> must be applied simultaneously or before V<sub>PP</sub> and removed simultaneously or after V<sub>PP</sub>.
- 3. When programming, a 0.1 µF capacitor is required between Vpp and GND to suppress spurious voltage transients, which can damage the device.
- 4. See AC Input/Output Reference Waveform for timing measurements.
- 5. top and topp are device characteristics but must be accommodated by the programmer.
- 6. Sampled, not 100% tested.



# **PROGRAMMING WAVEFORMS**



# **REVISION HISTORY**

Number	Description
002	Deleted - 120 PDIP package.
	Revised classification from Advance Information to Preliminary.
	Deleted Express Offerings.